

|           | <b>Hit<br/>s</b> | <b>Search Text</b>  | <b>DBs</b>   |
|-----------|------------------|---|--|
| <b>12</b> | 0                | ((resist or photoresist or photoimageable) same laminat\$4 same (substrate or wafer or carrier or release) same (expos\$4 or irradiat\$4 or illuminat\$4) same develop\$4 same cur\$4) and (cutter or cutt\$4) and (tack\$6) and (fold\$6) and ((resist or photoimageable or photoresist) same (liquid or ink) same (film or coat\$4 or deposit\$4 or form\$3 or layer) same (dry\$4 or heat\$4 or bak\$4) same (carrier or sheet or transfer or (temporary near5 sheet))) same transparent same laminat\$4)                    | US-PGPUB;<br>USPAT;<br>FPRS; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB |
| <b>13</b> | 0                | 430/311.ccls. and ((resist or photoresist or photoimageable) same laminat\$4 same (substrate or wafer or carrier or release) same (expos\$4 or irradiat\$4 or illuminat\$4)) and ((resist or photoimageable or photoresist) same (liquid or ink or fluid) same (film or coat\$4 or deposit\$4 or form\$3 or layer) same (dry\$4 or heat\$4 or bak\$4 or dried) same (carrier or sheet or transfer or (temporary near5 sheet))) same transparent same laminat\$4) and develop\$5 and cur\$3 and (cut\$5 or drill\$4) and fold\$6 | US-PGPUB;<br>USPAT;<br>FPRS; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB |

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| <b>14</b> | 0                | 430/330.ccls. and ((resist or photoresist or photoimageable) same laminat\$4 same (substrate or wafer or carrier or release) same (expos\$4 or irradiat\$4 or illuminat\$4)) and ((resist or photoimageable or photoresist) same (liquid or ink or fluid) same (film or coat\$4 or deposit\$4 or form\$3 or layer) same (dry\$4 or heat\$4 or bak\$4 or dried) same (carrier or sheet or transfer or (temporary near5 sheet)) same transparent same laminat\$4) and develop\$5 and (cur\$3 or heat\$4) and (cut\$5 or drill\$4) and fold\$6 | US-PGPUB;<br>USPAT;<br>FPRS; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB |
| <b>15</b> | 0                | 430/314.ccls. and ((resist or photoresist or photoimageable) same laminat\$4 same (substrate or wafer or carrier or release) same (expos\$4 or irradiat\$4 or illuminat\$4)) and ((resist or photoimageable or photoresist) same (liquid or ink or fluid) same (film or coat\$4 or deposit\$4 or form\$3 or layer) same (dry\$4 or heat\$4 or bak\$4 or dried) same (carrier or sheet or transfer or (temporary near5 sheet)) same transparent same laminat\$4) and develop\$5 and (cur\$3 or heat\$4) and (cut\$5 or drill\$4)             | US-PGPUB;<br>USPAT;<br>FPRS; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB |

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| <b>16</b> | 0                | 216/18.ccls. and ((resist or photoresist or photoimageable) same laminat\$4 same (substrate or wafer or carrier or release) same (expos\$4 or irradiat\$4 or illuminat\$4)) and ((resist or photoimageable or photoresist) same (liquid or ink or fluid) same (film or coat\$4 or deposit\$4 or form\$3 or layer) same (dry\$4 or heat\$4 or bak\$4 or dried) same (carrier or sheet or transfer or (temporary near5 sheet)) same transparent same laminat\$4) and develop\$5 and (cur\$3 or heat\$4) and (cut\$5 or drill\$4)  | US-PGPUB;<br>USPAT;<br>FPRS; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB |
| <b>17</b> | 0                | 174/254.ccls. and ((resist or photoresist or photoimageable) same laminat\$4 same (substrate or wafer or carrier or release) same (expos\$4 or irradiat\$4 or illuminat\$4)) and ((resist or photoimageable or photoresist) same (liquid or ink or fluid) same (film or coat\$4 or deposit\$4 or form\$3 or layer) same (dry\$4 or heat\$4 or bak\$4 or dried) same (carrier or sheet or transfer or (temporary near5 sheet)) same transparent same laminat\$4) and develop\$5 and (cur\$3 or heat\$4) and (cut\$5 or drill\$4) | US-PGPUB;<br>USPAT;<br>FPRS; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB |

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| <b>18</b> | 0                | 29/825.ccls. and ((resist or photoresist or photoimageable) same laminat\$4 same (substrate or wafer or carrier or release) same (expos\$4 or irradiat\$4 or illuminat\$4)) and ((resist or photoimageable or photoresist) same (liquid or ink or fluid) same (film or coat\$4 or deposit\$4 or form\$3 or layer) same (dry\$4 or heat\$4 or bak\$4 or dried) same (carrier or sheet or transfer or (temporary near5 sheet)) same transparent same laminat\$4) and develop\$5 and (cur\$3 or heat\$4) and (cut\$5 or drill\$4)           | US-PGPUB;<br>USPAT;<br>FPRS; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB |
| <b>19</b> | 0                | 29/825.ccls. and ((resist or photoresist or photoimageable) same laminat\$4 same (substrate or wafer or carrier or release) same (expos\$4 or irradiat\$4 or illuminat\$4)) and ((resist or photoimageable or photoresist) same (liquid or ink or fluid) same (film or coat\$4 or deposit\$4 or form\$3 or layer) same (dry\$4 or heat\$4 or bak\$4 or dried) same (carrier or sheet or transfer or (temporary near5 sheet)) same transparent same laminat\$4) and develop\$5 and (cur\$3 or heat\$4) and (cut\$5 or fold\$4 or tack\$5) | US-PGPUB;<br>USPAT;<br>FPRS; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB |